EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	20	("20030017645"|"20030020126"|"20030040138"|"5006673"|"5298687"|"5670797"|"6362525"|"6383835"|"6707247"|"6828510").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/24 14:54
L2	336	257/690,784,700,689,774,783,707,718,719,706,717.ccls. and @pd>"20060821"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/24 15:05
L3	0	((die chip) same (mounting adj pad) and LED).clm. and @pd>"20060821"	US-PGPUB	OR	ON	2006/11/24 15:11
L4	67	257/706,717,720.ccls. and @pd>"20060821"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/24 15:11
L5	2	(die chip) same (mounting adj pad) and LED and @pd>"20060821"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/24 15:14
L6	0	H01l adj 31/0224	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/24 15:15
S1	2	("5986885").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/24 14:54
S2	2	("6084295").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/08 10:25
S3	312	die same (mounting adj pad)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 10:26
S4	985	(die chip) same (mounting adj pad)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/31 12:59

S5	372	(die chip) same (mounting adj pad) same substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 10:27
S6	6	(("5986885") or ("6084295") or ("6620720")).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/22 12:01
S7	2226	(die chip IC) same (mount$3 with pad) same interconnect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/22 14:02
S8	7479	(die chip IC) same (bond$3 with pad) same interconnect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/22 14:02
S9	2123	(die chip IC) same (bond$3 with pad) same interconnect$3 same (hole via)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/22 14:38
S10	2	("6191477").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/22 14:38
S11	7	("5506755" | "5640048" | "5646826" | "5721454" | "5808873" | "5923084" | "6097089").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 14:57
S12	13	("3568000" | "3582865" | "3739469" | "4535385" | "4739448" | "4866841" | "5010641" | "5102829" | "5264729" | "5291062" | "5355283" | "5397917" | "5468999").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 15:00
S13	2	("4739448" | "4855537").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 15:02
S14	3226	(die chip) near3 pad near3 (metal copper cu)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/30 16:38

S15	1720	(die chip) near2 pad near2 (metal copper cu)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/30 16:39
S16	2	("5640048").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/31 12:55
S17	85	(die chip) same (mounting adj pad) and LED	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/24 15:12
S18	3146	257/690,784,700,689,774,783,707, 718,719,706,717,720.ccls. and @pd>"20040415"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/21 12:41
S19	3087	257/690,784,700,689,774,783,707, 718,719,706,717.ccls. and @pd>"20040415"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/24 15:05
S20	3031	257/690,784,700,689,774,783,707, 718,719,706.ccls. and @pd>"20040415"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/21 12:42
S21	2730	257/690,784,700,689,774,783,707, 718,719.ccls. and @pd>"20040415"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/21 13:12
S22	651	257/706,717,720.ccls. and @pd>"20040415"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/24 15:11
S23	6	((die chip) same (mounting adj pad) and LED).clm.	US-PGPUB	OR	ON	2006/11/24 15:11